

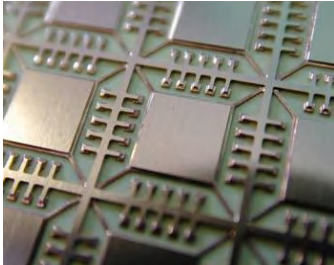
Thick Leadframe & Heat Slug for Power Devices



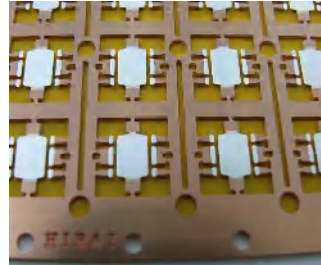
ETCHED LEADFRAME & HEAT SLUG (THICK METAL)

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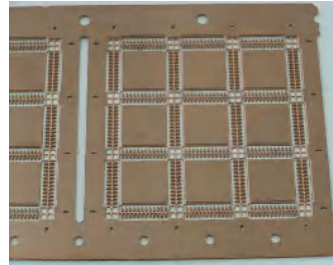
PRODUCTS



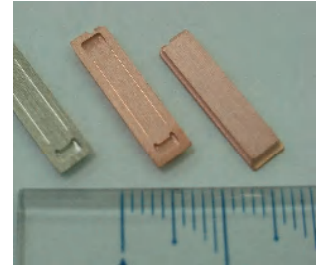
Standard QFN LF
Thickness 0.2mm
 (0.008")



QFN LF for Power Devices
Thickness 0.38mm
 (0,015")



QFN LF for Power Devices
Thickness 0.4mm
 (0.016")



Copper SLUG
Thickness 0.8mm
 (0.031")

FEATURES

-Thick Metal (0.35mm - 1.0mm / 0.0138" - 0.04")

Thick Metal of 0.35 – 1.0 mm (0.0318"-0.04") is available.

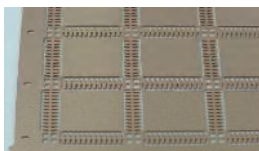
-Good Thermal Dissipation

Thick PAD and Heat Slug make good thermal dissipation. Our LF and Slug are better suited for High power applications.

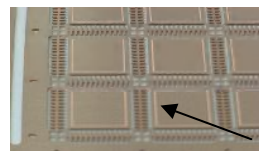
-Tight Mold Lock

Half etching process is provided. It makes tight mold lock.

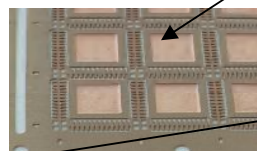
-Enable to form a Moat and/or Cavity on pad of LF and Slug.



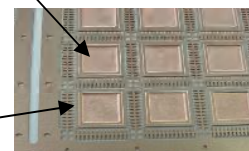
Standard



Moat



Cavity



Moat & Cavity

Advantages by having Moat 1) Bleed Control of D/A Epoxy, 2) Control of Solderability, 3) Moisture Control

Advantages by having Cavity 1) PKG of the Low Profile (Bond Line Thickness Control), 2) Control of D/A Epoxy Bleed & Solderability

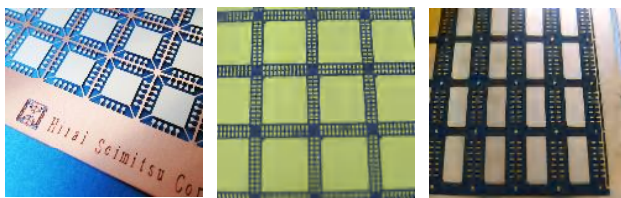
APPLICATIONS

-Power Devices

PKG for RF Modules, Power Amplifiers, RF Amplifiers, Driver Amplifiers.

-Power Management

PKG for Automotive components, Flat Screen Televisions, DVD Players, Music Players.



DESIGN RULE

Based on 0.38mm(0.015") thick metal

Items	Positions	Configurations	Specifications
A	Inner Lead Space		0.38 mm min. (0.30mm min.)
B	Space between Lead tip & Pad edge		0.38mm min (0.30mm min.)
C	Tie bar width		0.38mm min (0.3mm min.)
D	Half etch width of Inner lead		0.2 mm min. (0.1mm min.)
E	Half etch width at Pad edge		0.2 mm min. (0.1mm min.)

*Numbers in () is tentative advanced figures.